



Material Content Data Sheet



Sales Product Name		BTS7004-1EPP		Issued		4. July 2019		
MA#		MA005345074						
Package		PG-TSDSO-14-22		Weight*		65.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.355	2.08	2.08	20755	20755
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		144	
	non noble metal	zinc	7440-66-6	0.038	0.06		578	
	non noble metal	iron	7439-89-6	0.754	1.16		11551	
wire	non noble metal	copper	7440-50-8	30.617	46.91	48.14	469006	481279
	non noble metal	copper	7440-50-8	0.792	1.21	1.21	12137	12137
	organic material	carbon black	1333-86-4	0.086	0.13		1324	
encapsulation	plastics	epoxy resin	-	3.371	5.16		51638	
	inorganic material	silicondioxide	60676-86-0	25.354	38.84	44.13	388387	441349
leadfinish	non noble metal	tin	7440-31-5	1.642	2.51	2.51	25147	25147
plating	noble metal	silver	7440-22-4	0.816	1.25	1.25	12501	12501
glue	plastics	epoxy resin	-	0.078	0.12		1196	
	noble metal	silver	7440-22-4	0.368	0.56	0.68	5636	6832
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com